phototransistor



Features

Narrow angular response Durable High reliability in demanding environments

Application

Optical switches Optical detectors Infrared sensors Encoders Smoke detectors

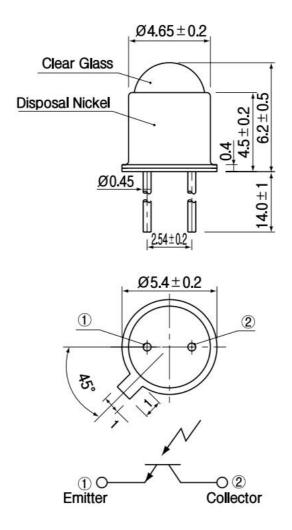
Description

The ST-1KLA is a high-sensitivity NPN silicon phototransistors mounted in durable, hermetically sealed TO-18 metal can which provide years of reliable performance, even under demanding conditions such as use outdoors.





PACKAGE DIMENSIONS



NOTES:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25mm(.010") unless otherwise noted.
- 3. Lead spacing is measured where the leads emerge from the package.

PHOTOTRANSISTOR **ST-1KLA**



MAXIMUM RATINGS

MAXIMUM RATINGS (Ta=25°C)						
Item	Symbol	Rating	Unit			
C-E voltage	Vceo	40	V			
E-C voltage	Veco	6	V			
Collector current	lc	50	mA			
Collector power dissipation	Pc	150	mW			
Operating temp.	Topr.	-30~+100	°C			
Storage Temp.	Tstg.	-50~+150	°C			
Soldering temp. *1	Tsol.	260	°C			

*1. For MAX.5 seconds at the position of 2 mm from the package

ELECTRO-OPTICAL CHARACTERISTICS

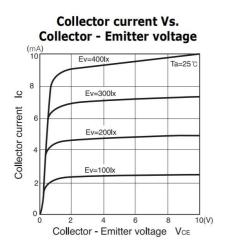
(Ta=25°C)

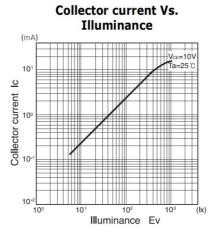
Item	ו	Symbol	Conditions	Min.	Тур.	Max.	Unit.
Collector dark curr	ent	CEO	$V_{CEO} = 10V$		1	200	nA
Light current		L	VCE = 10V, 2001x *2	1.5	5.0	15	mA
C-E saturation vol	tage	VCE(sat)	lc=5mA, 2,000lx *2		0.2	0.4	V
Switching speeds	Rise time	tr	Vcc=10V, $Ic=5mA$,		3.2		µsec.
	Fall time	tf	$R_{L}=100\Omega$		4.8		µsec.
Spectral sensitivity		λ		500~1,050 nm		nm	
Peak wavelength		λр			880		nm
Half anglee		Δθ			± 8		deg.

*2. Color temp.=2856K standard Tungsten lamp

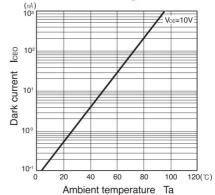
PHOTOTRANSISTOR ST-1KLA



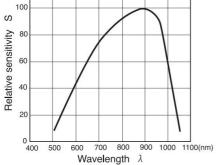


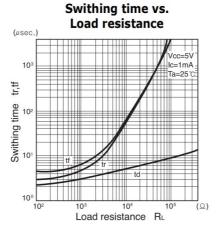


Dark current Vs. Ambient temperature



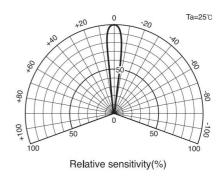
Relative sensitivity Vs. Wavelength

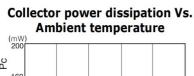


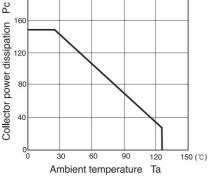


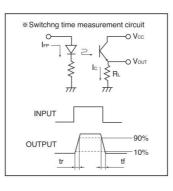
Radiant Pattern

Angle (deg.)









PHOTOTRANSISTOR



Packing Quantity Specification

- 1. 500Pcs/1Bag,20 Bag/1Box
- 2. 4Boxes/1Carton

Label Form Specification



- · PRODUCT: Part Number
- · CODE NO.: Product Serial Number
- · QTY: Packing Quantity
- · LOT No: Lot Number
- · REMARKS:Remarks

Notes Lead Forming

1. During lead frame bending, the lead frame should be bent at a distance more than 3mm from bottom of the epoxy.

Note: Must fix lead frame and do not touch epoxy before bending to avoid Phototransistors broken.

2.Lead forming should be done before soldering.

3. Avoid stressing the Phototransistor package during leads forming. The stress to the base may damage the Phototransistor's characteristics or it may break the Phototransistors.

4.Cut the Phototransistor lead frame at room temperature. Cutting the lead frame at high temperatures may cause failure of the Phototransistors.

5. When mounting the Phototransistors onto a PCB, the PCB holes must be aligned exactly with the lead position of the Phototransistor. If the Phototransistors are mounted with stress at the leads, it causes deterioration of the epoxy resin and this will degrade the Phototransistors.

PHOTOTRANSISTOR



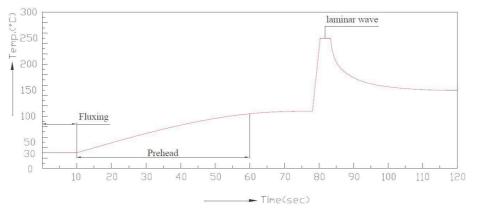
Soldering

1. Careful attention should be paid during soldering. When soldering, leave more than 3mm from solder joint to epoxy bulb, and soldering beyond the base of the tie bar is recommended.

2. Recommended soldering conditions:

Hand	dSoldering	DIP Soldering		
Temp. at tip of iron	300°C Max. (30W Max.)	Preheat temp.	100°C Max. (60 sec Max.)	
Soldering time	3 sec Max.	Bath temp. & time	260 Max., 5 sec Max	
	3mm Min.(From solder		3mm Min. (From solder joint	
Distance	joint to epoxy bulb)	Distance	to epoxy bulb)	

3. Recommended soldering profile



4. Avoiding applying any stress to the lead frame while the Phototransistors are at high temperature particularly when soldering.

5. Dip and hand soldering should not be done more than one time

6.After soldering the Phototransistors, the epoxy bulb should be protected from mechanical shock or vibration until the Phototransistors return to room temperature.

7.A rapid-rate process is not recommended for cooling the Phototransistors down from the peak temperature.

8. Although the recommended soldering conditions are specified in the above table, dip or hand soldering at the lowest possible temperature is desirable for the Phototransistors.

9. Wave soldering parameter must be set and maintain according to recommended temperature and dwell time in the solder wave.



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